

Applicant(s): Wade D. Vinson et al.

Title: Heat Sink Having Compliant Interface  
to Span Multiple Components

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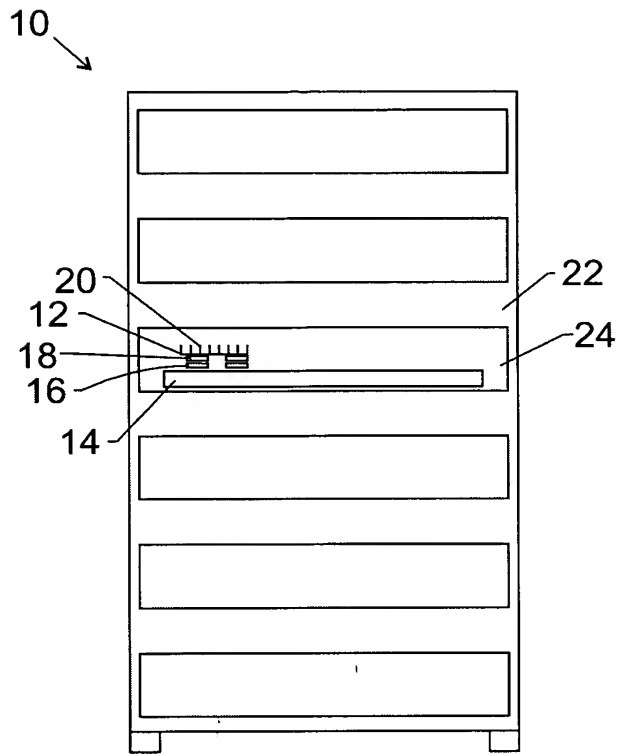


FIG. 1

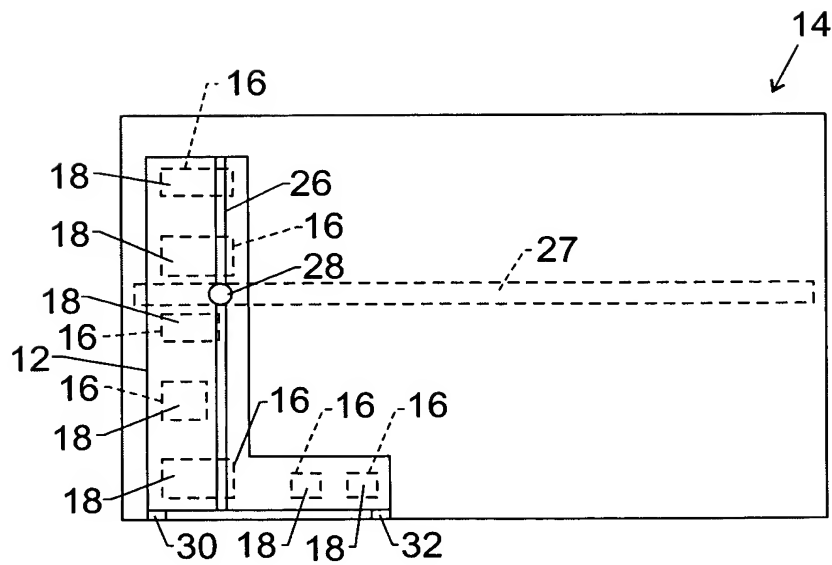


FIG. 2

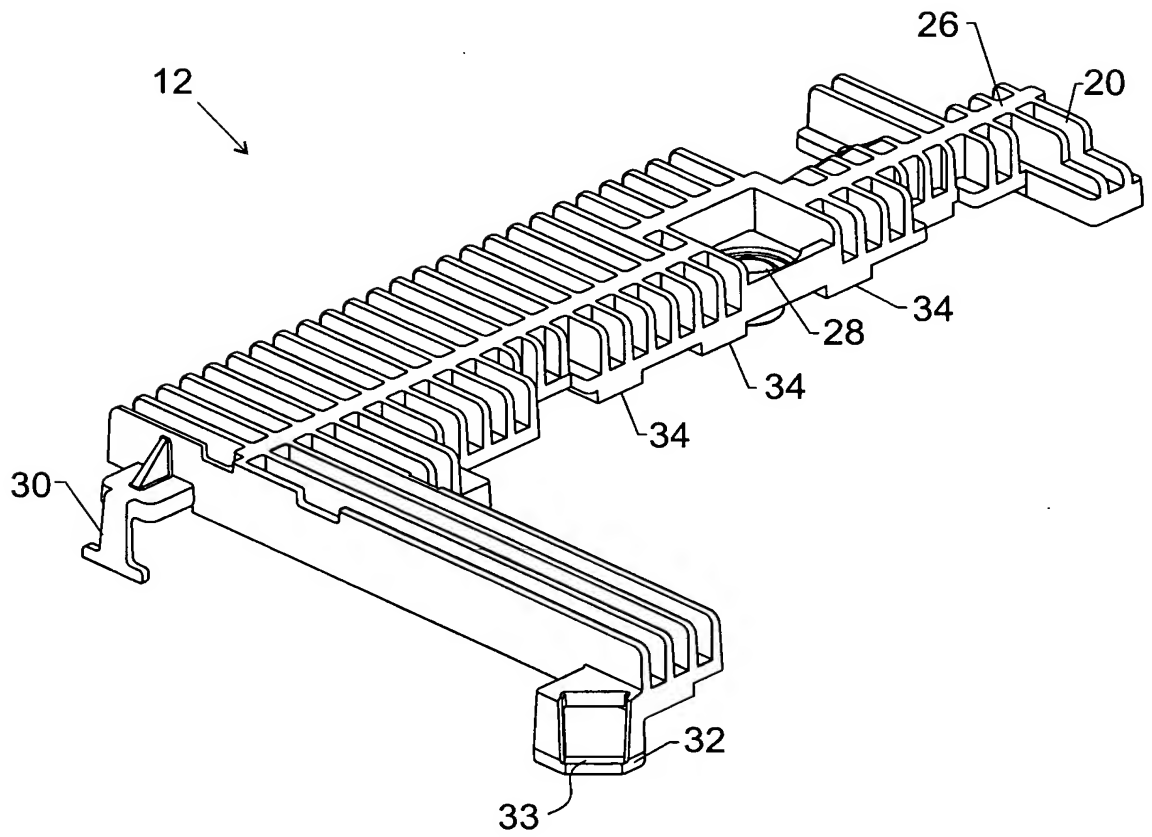


FIG. 3

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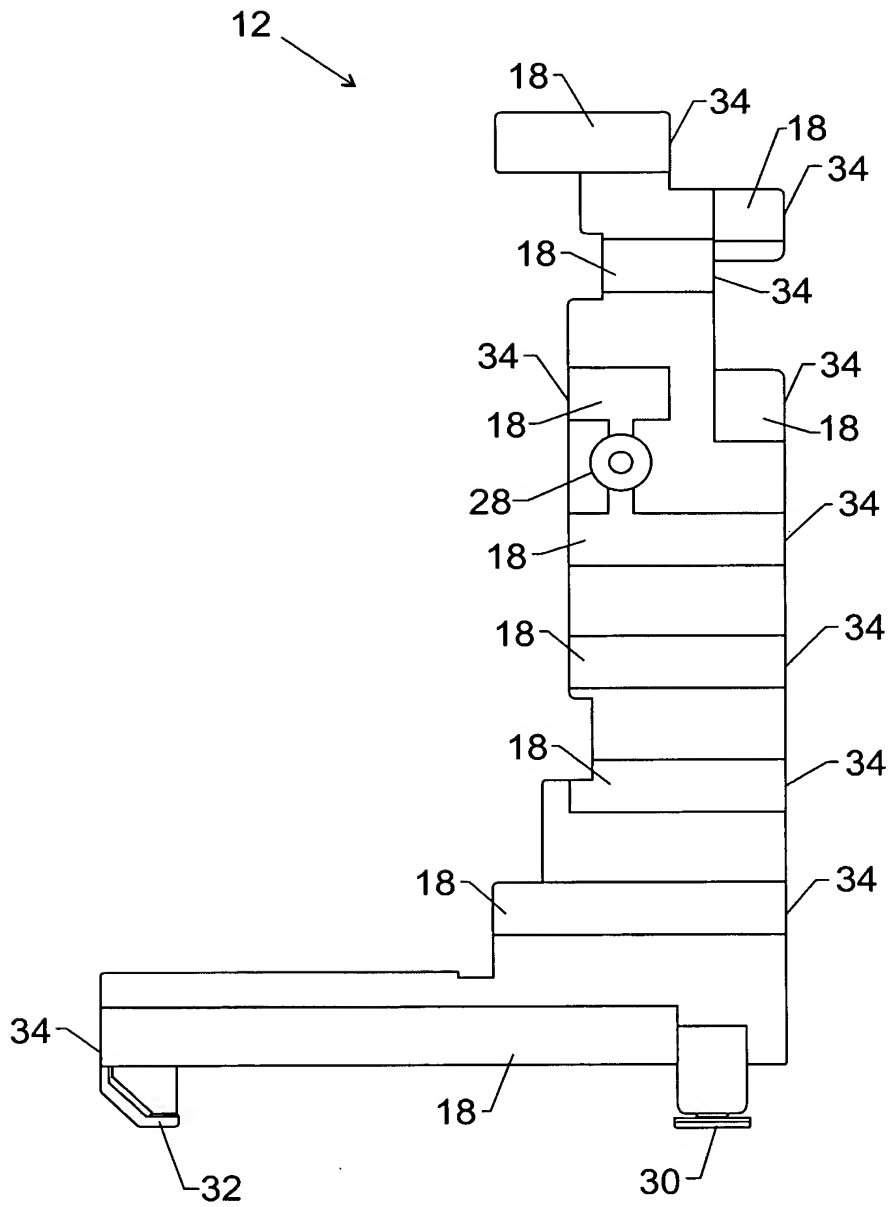


FIG. 4

